Processor heat sink module

Entry and performance

Different types of processor heat sink module - Entry

The processor heat sink module (PHM) refers to a subassembly of a heat sink and processor that have been clipped together prior to installation. This allows for a more robust installation by providing better alignment, and it also reduces the chances of people touching the socket contact field. The ThinkSystem V2 supports two types of PHM: Entry and Performance. The Entry PHM is suitable for processors with a TDP of 150 to 165 watts.

Processor
Carrier

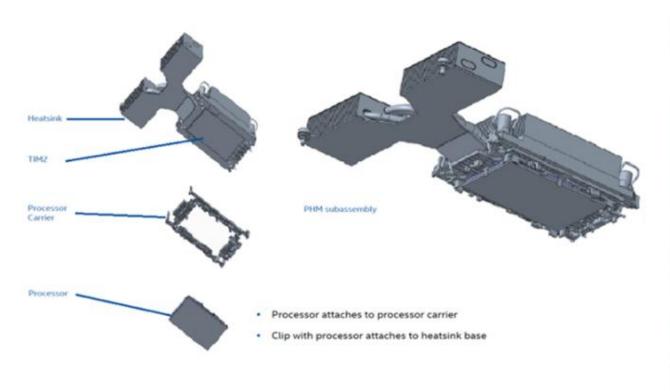
Processor

- Processor attaches to processor carrier
- Clip with processor attaches to heatsink base



Different types of processor heat sink module - Performance

The Performance PHM is suitable for processors with a TDP of 165 to 250 watts.





Note: Refer to each individual ThinkSystem V2 server YouTube or Youku channel for PHM installation/removal instructions – for example, the SR860 V2 <u>YouTube</u> or <u>Youku</u> channels.

Summary

This course enabled you to:

- Describe the features of the 3rd Generation Intel Xeon Scalable processor
- Identify the differences between the 1st Generation, 2nd Generation, and 3rd Generation Intel Xeon Scalable processors
- Describe the different processor heat sink modules (PHMs) used in ThinkSystem V2 servers
- Describe the Intel Xeon Scalable processor naming rules
- Describe ThinkSystem server supported memory and storage features

